

Amendments to the Claims

This listing of claims will replace all prior versions and listings of claims in the application:

Listing of Claims

1. (currently amended) A method of cleaning and decontaminating the internal working components of a piece of electronic equipment along a predetermined media path, comprising the steps of:

[determining the distance between opposing internal working components along the predetermined media path when the piece of electronic equipment is disposed in a normally engaged position;]

providing a base material having first and second surfaces and a thickness, the base material including a cleaning substrate disposed on [at least] the first surface for cleaning at least one internal working component of the electronic equipment and an adhesive substrate disposed on [at least] the first surface for decontaminating the internal working component of the electronic equipment when the electronic equipment is disposed in a normally engaged position, wherein the thickness of the base material is [dependent upon the distance between internal working components along the predetermined media path] configured to assure contact with the internal working components when the piece of electronic equipment is disposed in a normally engaged position; and

feeding said base material through the piece of electronic equipment for cleaning when the internal working components are disposed in a normally engaged position.

2. (currently amended) A method of cleaning and decontaminating the internal working components of a piece of electronic equipment along a predetermined media path, comprising the steps of:

providing a base material having first and second surfaces, the base material including a cleaning substrate disposed on [at least] the first surface for cleaning at least one internal working component of the electronic equipment and an adhesive substrate disposed on [at least] the first surface for decontaminating the internal working components of the electronic equipment; and

feeding the base material through the piece of electronic equipment for cleaning the internal working components, said feeding taking place when the internal working components are disposed in a normally engaged position.

3. (previously presented) A method of cleaning and decontaminating the internal working components of a piece of electronic equipment along a predetermined media path according to claim 2 wherein said cleaning substrate of said providing step is selected from the group consisting of: aluminum oxide, calcined alumina, cerium oxide, chromium oxide, diamond, ferrous oxide, silicon carbide, silicon dioxide and cubic boron nitrate minerals.

4. (previously presented) A method of cleaning and decontaminating the internal working components of a piece of electronic equipment along a predetermined media path according to claim 2 wherein said base material of said providing step includes a lapping film.

5. (previously presented) A method of cleaning and decontaminating the internal working components of a piece of electronic equipment along a predetermined media path according to claim 2 wherein said second surface of said providing step includes at least one of said cleaning substrate and said adhesive substrate.

6. (previously presented) A method of cleaning and decontaminating the internal working components of a piece of electronic equipment along a predetermined media path according to claim 5 wherein said cleaning substrate and said adhesive substrate of said providing step are disposed on said first surface in strips in an alternating manner.

7. (previously presented) A method of cleaning and decontaminating the internal working components of a piece of electronic equipment along a predetermined media path according to claim 2 wherein said base material of said providing step is semi-compliant.

8. (currently amended) A method of cleaning and decontaminating the internal working components of a piece of electronic equipment along a predetermined media path according to claim 2 wherein said base material of said providing step is dimensioned in [the] a shape of a data-carrying card.

9. (currently amended) A method of cleaning and decontaminating the internal working components of a piece of electronic equipment along a predetermined media path according to claim 2 wherein said adhesive substrate of said providing step includes a first adhesive for adhering to [said] at least one of said first and second surfaces of said base material and a second adhesive for decontaminating said internal working components as said cleaning apparatus moves along the predetermined media path.

10. (currently amended) A method of cleaning and decontaminating the internal working components of a piece of electronic equipment along a predetermined media path according to claim 2 wherein a first side of said adhesive substrate of said providing step is thermally incorporated onto [said] at least one of said first and second surfaces of said base material and a second side of said adhesive substrate of said providing step includes an adhesive for decontaminating said internal working components as said cleaning apparatus moves along the predetermined media path.

11. (previously presented) A method of cleaning and decontaminating the internal working components of a piece of electronic equipment along a predetermined media path according to claim 2 wherein said adhesive substrate of said providing step is selected from the group consisting of: pressure sensitive adhesives, contact adhesives, aerosol adhesives, epoxies, solvent-based adhesives, water-based adhesives, curing adhesives, cyanoacrylate adhesives, heat-activated & heat re-activated adhesives and cohesive adhesives.

12. (previously presented) A method of cleaning and decontaminating the internal working components of a piece of electronic equipment along a predetermined media path according to claim 2 wherein one of said adhesive substrate and said cleaning substrate of said providing step is disposed over an edge of said base material.

13. (new) An apparatus for cleaning and decontaminating the internal working components of a piece of electronic equipment, comprising:

a base material having first and second surfaces, a thickness, a leading end and a trailing end; and

an adhesive cleaning strip incorporated on the base material, whereby the base material is fed through the piece of electronic equipment for cleaning when the internal working components of the equipment are disposed in a normally engaged position.

14. (new) The apparatus of claim 13, wherein the adhesive cleaning strip is used to clean at least one of reading, writing and scan heads (r/w/s heads).

15. (new) The apparatus of claim 14 wherein the adhesive cleaning strip is used to clean at least one of a reading, writing and scan head of a printer.

16. (new) The apparatus of claim 13 wherein the adhesive cleaning strip is incorporated at the leading end of the base material.

17. (new) The apparatus of claim 13 wherein the adhesive cleaning strip is incorporated at the trailing end of the base material.

18. (new) The apparatus of claim 13 wherein the adhesive cleaning strip is incorporated between the leading end and the trailing end of the base material.

19. (new) The apparatus of claim 13 wherein a plurality of the adhesive cleaning strips are incorporated on the base material.

20. (new) The apparatus of claim 13 wherein the base material is configured as a roll of labels.

21. (new) The apparatus of claim 20 wherein the adhesive cleaning strip replaces at least one label of the roll of labels.

22. (new) The apparatus of claim 13 wherein the adhesive cleaning strip includes a cleaning substrate.

23. (new) The apparatus of claim 22 wherein the cleaning substrate is selected from the group consisting of aluminum oxide, calcined alumina, cerium oxide, chromium oxide, diamond, ferrous oxide, silicon carbide, silicon dioxide and cubic boron nitrate minerals.

24. (new) An apparatus for cleaning and decontaminating the internal working components of a piece of electronic equipment, comprising:

a base material configured as a roll having first and second surfaces, a thickness, a leading end and a trailing end; and

an adhesive cleaning strip incorporated on one end of the base material, whereby the base material is fed through the piece of electronic equipment for cleaning when the internal working components of the equipment are disposed in a normally engaged position.

25. (new) A method of cleaning a head of a printer, comprising the steps of:

providing a base material configured as a roll;

providing an adhesive strip including a cleaning substrate disposed thereon for cleaning a head of a printer;

applying the adhesive strip to one end of the base material;

feeding the base material into the printing path of a printer; and

moving the base material at least partially through a printer such that the adhesive strip cleans at least a head of a printer.